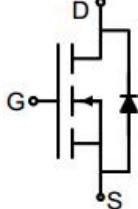
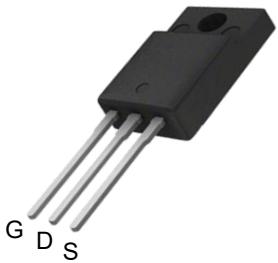


N-Channel Enhancement Mode Power MOSFET

<p>Description</p> <p>The G58N06F uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.</p> <p>General Features</p> <ul style="list-style-type: none"> ● V_{DS} 60V ● I_D (at $V_{GS} = 10V$) 35A ● $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 13mΩ ● $R_{DS(ON)}$ (at $V_{GS} = 4.5V$) < 15mΩ ● 100% Avalanche Tested ● RoHS Compliant <p>Application</p> <ul style="list-style-type: none"> ● Power switch ● DC/DC converters 	 <p>Schematic diagram</p>  <p>TO-220F</p>
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Ordering Information			
Device	Package	Marking	Packaging
G58N06F	TO-220F	G58N06	50pcs/Tube

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Continuous Drain Current	I_D	35	A
Pulsed Drain Current (note1)	I_{DM}	140	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	P_D	44	W
Single pulse avalanche energy (note2)	E_{AS}	100	mJ
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	°C

Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	R_{thJA}	60	°C/W
Maximum Junction-to-Case	R_{thJC}	2.8	°C/W

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	1.9	2.4	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 30\text{A}$	--	10	13	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 25\text{A}$	--	12	15	
Forward Transconductance	g_{FS}	$V_{\text{GS}} = 5\text{V}, I_D = 30\text{A}$	--	83	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 30\text{V}, f = 1.0\text{MHz}$	--	3006	--	pF
Output Capacitance	C_{oss}		--	161	--	
Reverse Transfer Capacitance	C_{rss}		--	143	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = 30\text{V}, I_D = 30\text{A}, V_{\text{GS}} = 10\text{V}$	--	75	--	nC
Gate-Source Charge	Q_{gs}		--	13.5	--	
Gate-Drain Charge	Q_{gd}		--	19.5	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 30\text{V}, I_D = 30\text{A}, R_G = 3\Omega$	--	60	--	ns
Turn-on Rise Time	t_r		--	21	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	69	--	
Turn-off Fall Time	t_f		--	48	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	35	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 30\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V
Reverse Recovery Charge	Q_{rr}	$I_F = 30\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A}/\mu\text{s}$	--	147	--	nC
Reverse Recovery Time	T_{rr}		--	87	--	ns

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$
3. Identical low side and high side switch with identical R_G

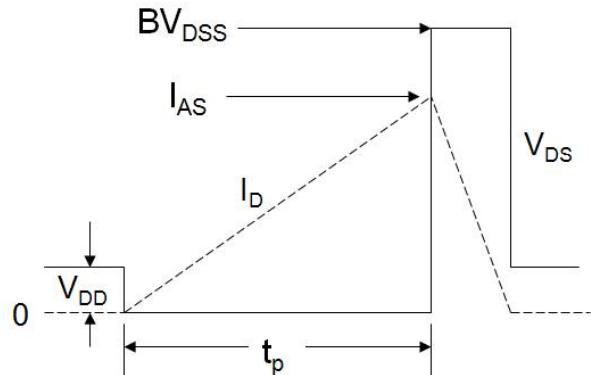
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

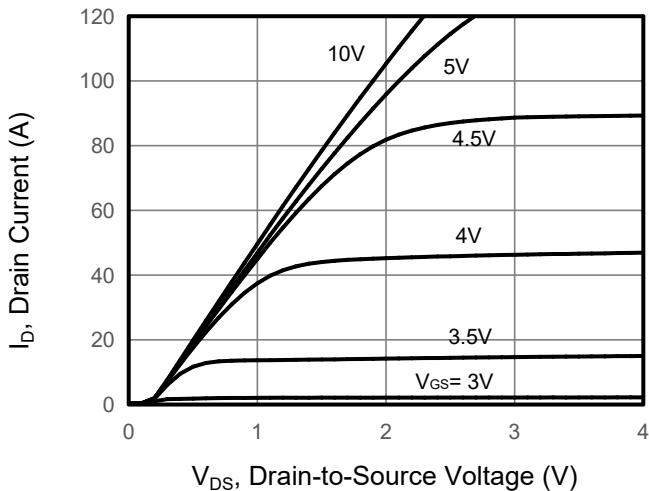


Figure 2. Transfer Characteristics

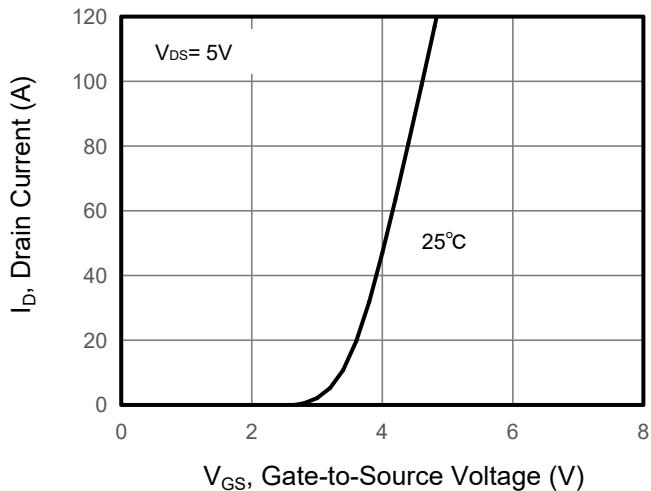


Figure 3. Drain Source On Resistance

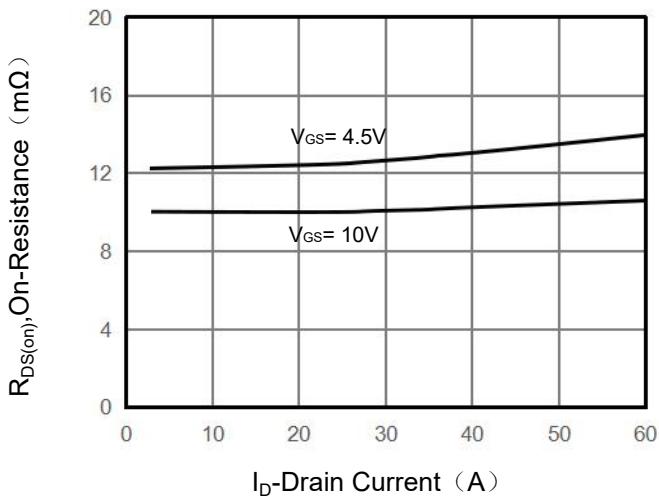


Figure 4. Gate Charge

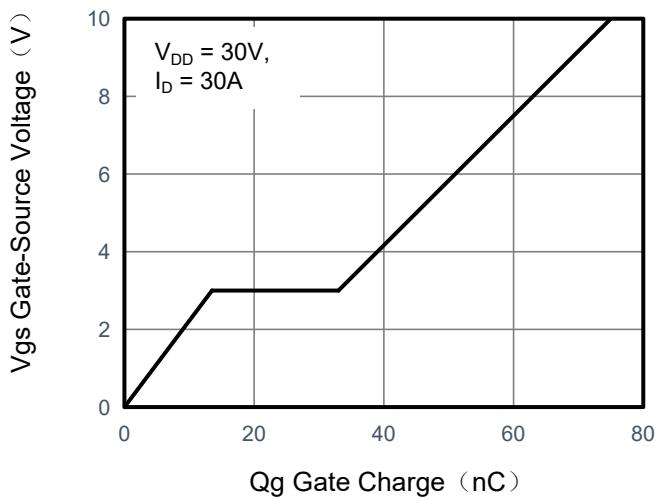


Figure 5. Capacitance

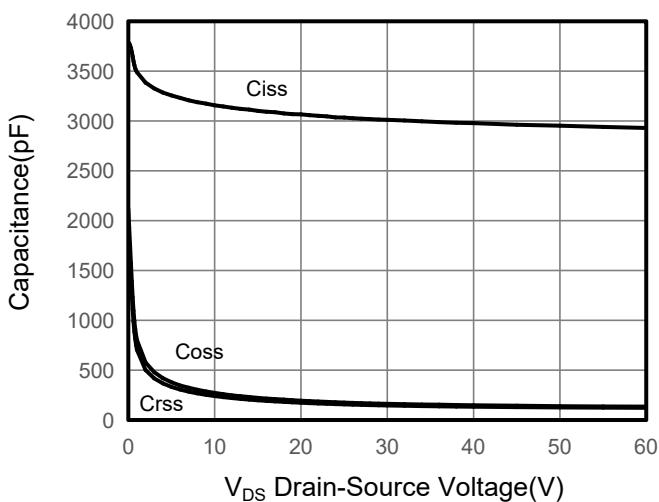
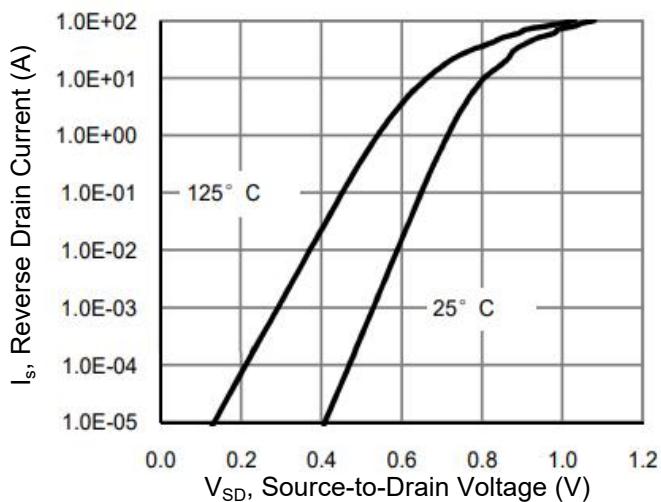


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

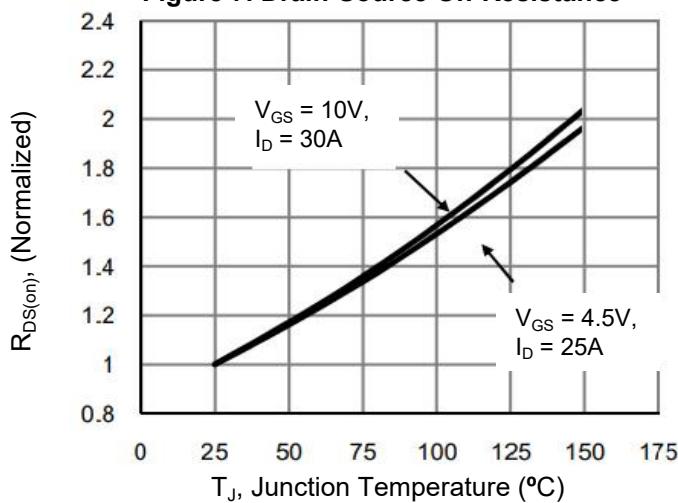


Figure 8. Safe Operation Area

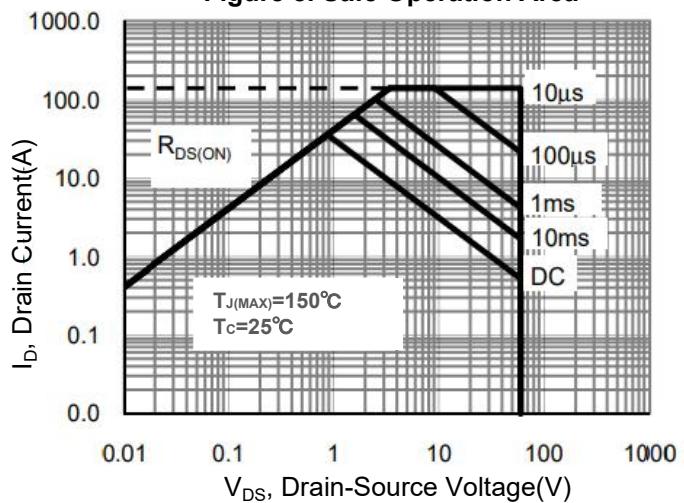
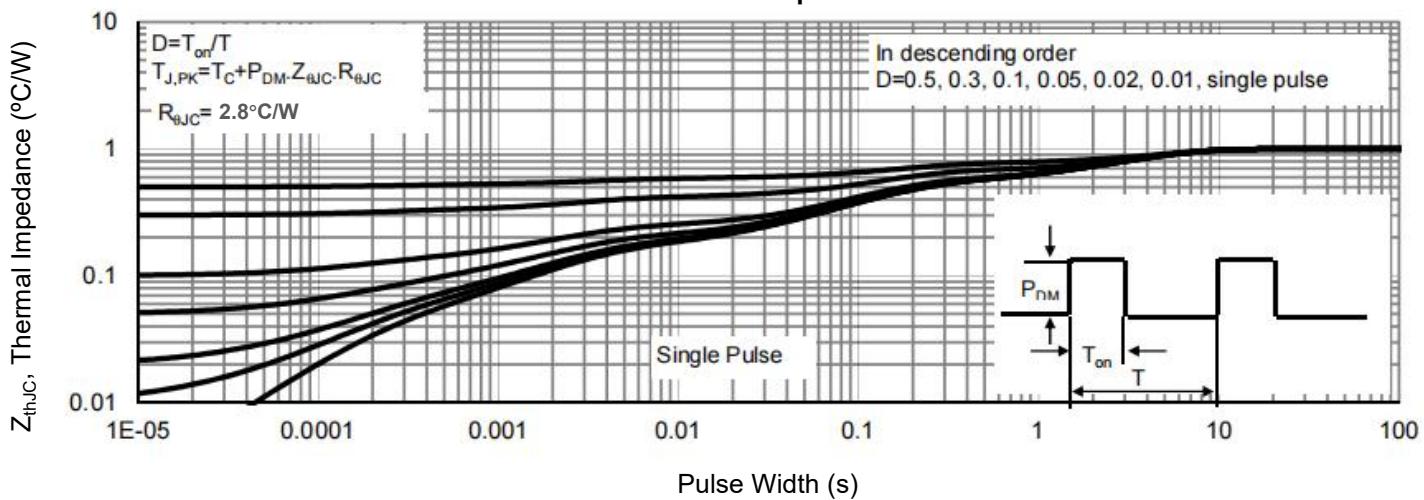
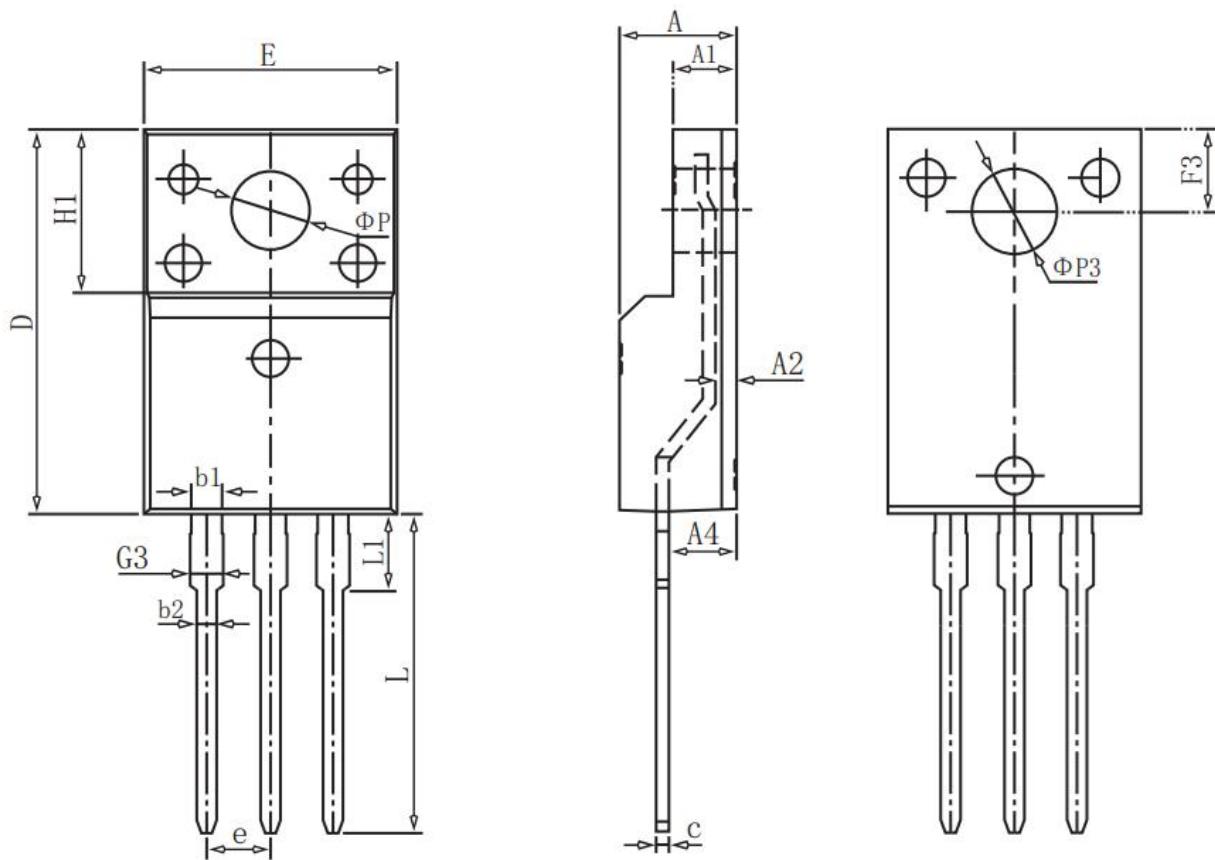


Figure 9. Normalized Maximum Transient Thermal Impedance



TO-220F Package Information**COMMON DIMENSIONS**

SYMBOL	mm		
	MIN	NOM	MAX
E	10.00	10.20	10.40
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A2	0.65	0.85	1.30
A4	2.55	2.75	2.95
c	0.40	0.50	0.65
D	15.57	15.87	16.17
H1		6.70REF	
e		2.54BSC	
ΦP		3.183REF	
L	12.68	12.98	13.28
L1	3.25	3.45	3.65
$\Phi P3$		3.45REF	
F3	3.10	3.30	3.50
G3	1.10	1.30	1.50
b1	1.05	1.20	1.35
b2	0.70	0.80	0.92